

LAMP2025

The 9th International Congress on Laser Advanced Materials Processing

LPM2025 The 26th International Symposium on Laser Precision Microfabrication

HPL2025 The 9th International Symposium on High Power Laser Processing



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Date June 10-13, 2025

Venue Sinfonia Technology Hibiki Hall Ise <https://www.ise-kanbun.jp/>
Ise-city, Mie-prefecture, Japan <https://www.iseshima-kanko.jp/en>

Organizer Japan Laser Processing Society (JLPS) <http://www.jlps.gr.jp/>

Aim and Scope

The International Congress on Laser Advanced Materials Processing (LAMP) deals with the science and technology of advanced laser materials processing, covering precision microfabrication and high-power laser processing. LAMP2025 will be held from June 10-13, 2025, in Ise City, Mie Prefecture, Japan.

LAMP2025 consists of two international symposia: Laser Precision Microfabrication (LPM) and High Power Laser Processing (HPL). It covers hardware and software for fundamental research and industrial applications in both micro and macro processing.

LAMP2025 is planned as a four-day event featuring a Plenary Session, Oral and Poster Sessions, LPM Special Sessions focusing on topical issues, and an exhibition hosting prominent figures in this field worldwide. The aim of this congress is to provide a forum for discussing fundamental aspects of laser-matter interaction, the state-of-the-art in laser materials processing, and next-generation topics with fundamental scientists, end-users, and laser manufacturers.

We anticipate that LAMP2025 will play an important role not only in advancing the understanding of fundamental laser materials processing but also in forecasting future technologies and trends in the laser market.

Committees

- General Chair : **Yasuhiro Okamoto**, Okayama University, Japan
- Co-Chairs : **Mitsuhiro Terakawa**, Keio University, Japan (LPM2025 Program Chair)
Masahiro Tsukamoto, JWRI, Osaka University, Japan (HPL2025 Program Chair)
Yongfeng Lu, University of Nebraska-Lincoln, USA
Michael Schmidt, Friedrich-Alexander Universität Erlangen-Nürnberg, Germany
- Steering Committee Chair : **Yoichiroh Hosokawa**, Nara Institute of Science and Technology, Japan
- Treasurer Leader : **Yasutaka Hanada**, Hirosaki University, Japan
- Honorary Chairs : **Isamu Miyamoto**, Emeritus Prof., Osaka University, Japan
Koji Sugioka, RIKEN, Japan
Hiroyuki Niino, AIST, Japan



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Congress website

<http://www.jlps.gr.jp/lamp/lamp2025/>

LAMP2025 TOPICS

LPM2025 TOPICS

1. Fundamental aspects (Dynamics, modeling, simulation, etc.)
2. Laser and photochemistry
3. Ultra-short pulse laser processing
4. Burst ablation
5. Advanced laser processing (Fiber laser, disc laser, FEL, etc.)
6. Glass/Ceramic processing
7. VUV laser and X-ray processing
8. Nanotechnology
9. Nano-ripple formation
10. Nano- and micro-particles (including laser synthesis and processing in liquids)
11. Micro-machining
12. Micro-drilling and micro-cutting
13. Micro-welding and micro-bonding
14. Micro-forming
15. Micro-patterning and micro-structuring
16. Surface processing (Texturing, cleaning, annealing, modification, etc.)
17. 3-D micro- and nano-fabrication
18. Film deposition and synthesis of advanced materials (PLD, CVD, etc.)
19. Laser-based direct-write techniques
20. Laser-induced forward transfer (LIFT) techniques
21. Lithography (including EUV source and application)
22. Laser devices
23. Beam shaping
24. Optics and systems for laser microprocessing
25. Process monitoring and control
26. Packaging and mounting process
27. Manufacture of micro devices and systems
28. Medical and biological applications
29. Industrial applications
30. Others
31. Special Session : TBA

HPL2025 TOPICS

1. Fundamentals of laser-materials interactions
2. Laser-induced plasma/plume
3. Gas laser
4. Solid-state laser (YAG, Fiber, Disk, etc.)
5. Diode laser
6. Green or blue laser
7. Optics
8. Beam delivery system
9. Monitoring and control (including OCT)
10. Metallurgical and mechanical aspects
11. Modeling and simulation
12. Cleaning
13. Surface modification (Hardening, quenching, alloying, etc.)
14. Cladding and rapid prototyping
15. Additive manufacturing (3D Printer)
16. Welding
17. Welding of thick plate
18. Welding of high strength steel
19. Welding of light metals and alloys
20. Joining of plastics, glasses or ceramics
21. Joining of dissimilar materials (plastic to metal)
22. Joining of battery or fuel cell
23. Remote welding
24. Hybrid welding
25. Brazing and soldering
26. Drilling (High speed and high quality)
27. Cutting (of CFRP, etc.)
28. Thick plate cutting and dismantling
29. Industrial applications
30. Innovative applications (Sandwich panel, etc.)
31. Present status and future prospects
32. Others

CONTACT

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